

ORDERING INFORMATION

PART IDENTIFIER: SMT2010

ASSEMBLY DWG: 1101154

SPECIFICATIONS

1. ELECTRICAL:

Impedance:	50 Ω Nominal.
Frequency:	DC - 2 GHz.
VSWR:	1.25:1 Max.
Input Power:	30 Watts. Chip Soldered to Mounting Surface. Mounting Surface Temperature Maintained At 100°C Maximum. Apply Linear De-Rating of Input Power To 0 Watts At 150°C.

2. ENVIRONMENTAL:

Non-Operating Temperature:	-55°C To +150°C.
Operating Temperature:	-55°C To +150°C.

3. MARKING:

Unit Marking:	No Marking.
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4. QUALITY ASSURANCE:

Sample Inspect Per ANSI/ASQC Z1.4 General Inspection, Level II, AQL = 1.0.

Visual And Mechanical Per 824W154.

Dc Resistance: 50 Ω \pm 5 %.

Data Requirements:

- No Test Data Required for Customer.
- Data Retention – 24 Months.

5. PACKAGING:

Standard Packaging:	Standard Pack Per 755W002.
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6. MECHANICAL:

Workmanship:	Per MIL-PRF-55342.
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Thermal Impedance (R θ)

1.667 °c / watt r θ from resist film to mounting surface directly under center of chip.

chip soldered directly to mounting surface.

Film Temperature (T_f):

200°C absolute maximum film temperature. de-rate to 150 °c maximum film temperature for all military/high-reliability applications.

Thermal:

Determine maximum mounting surface temperature by applying the following formula:

$$T_S = T_F - (P_{MAX} \times R_{\theta})$$

Where:

T_S = Maximum Mounting Surface Temperature.

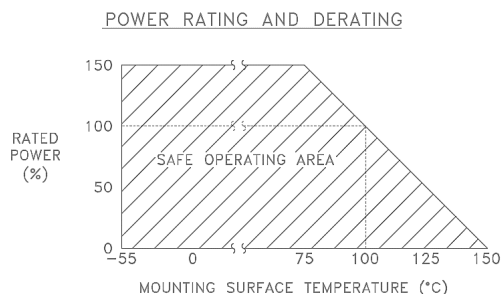
T_F = Maximum Film Temperature.

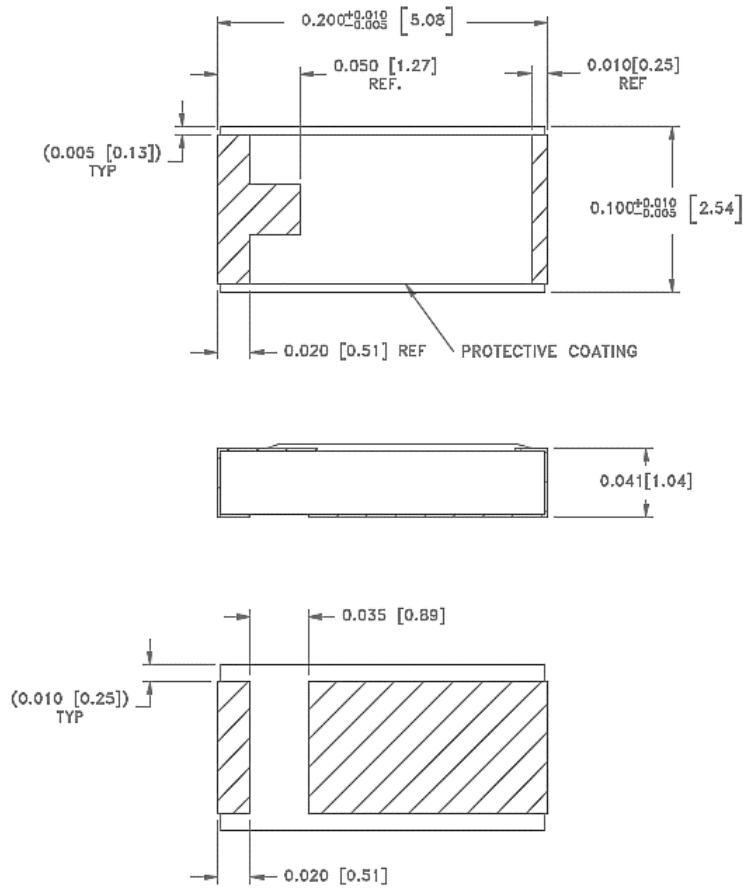
P_{MAX} = Maximum Applied Input Power.

R_θ = Chip Thermal Impedance.

Mechanical Specifications:

Substrate:	Beryllia, ASTM F356
Terminals:	Thick Film, Nickel Barrier, Solder Plated
Resist:	Thick Film





Unless Otherwise Specified:

Tolerance: X.XX = ± 0.00 X.XXX = ± 0.005.

Metric equivalents given in [mm] are for reference information only.